Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	577	@ad<="20020111" and (438/455). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:44
S2	158	@ad<="20020111" and (438/456). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:40
S3	53	@ad<="20020111" and (438/457). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:57
S4	375	@ad<="20020111" and (438/458). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:58
S5	548	@ad<="20020111" and (438/459). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:58
S6	453	@ad<="20020111" and (438/460). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:58
S 7	363	@ad<="20020111" and (427/289). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S8	292	@ad<="20020111" and (451/53). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:03
S9	2016	@ad<="20020111" and (438/690-692).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:19
S10	249	@ad<="20020111" and (451/44). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41

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S11	363	@ad<="20020111" and (427/289). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:05
S12	312	@ad<="20020111" and (257/e21. 237).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S13	292	@ad<="20020111" and (257/e21. 23).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:13
S14	393	@ad<="20020111" and (257/618). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S15	454	@ad<="20020111" and (257/620). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 09:24
S16	151	@ad<="20020111" and (438/413). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:19
S17	154	@ad<="20020111" and (257/e21. 238).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S18	252	@ad<="20020111" and (257/e21. 239).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S19	303	@ad<="20020111" and (257/e21. 002).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S20	183	@ad<="20020111" and (257/e21. 022).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:42
S21	1	'9-251934'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:24

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S22	116	'shin-etsu' and 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:25
S23	1	'JP 9-251934'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:04
S24	1	'JP09251934'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:20
S25	2	'09251934'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:21
S26	3	'06061201'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:23
S27	3	"02275613"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:23
S28	76	'shin-etsu handotai' and 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 13:46
S29	336	'hitachi Itd' and 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:26
S30	33	'hitachi Itd' and 'wafer' same 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 14:08
S31	70	'shin-etsu' and 'wafer' same 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:50
S32	191	@ad<="20020111" and 'wafer' and 'chamfered' same 'polished'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/02 13:00

S33	2	@ad<="20020111" and 'wafer' and 'chamfered' same 'polished' and 'non-mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:54
S34	2	@ad<="20020111" and 'wafer' and 'chamfered' and 'polished' and 'non-mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:54
S35	8	@ad<="20020111" and 'wafer' and 'chamfered' and 'polished' and 'unpolished'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:57
S36	23	@ad<="20020111" and 'wafer' and 'chamfered' same 'mirror finished'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:58
S37	23	@ad<="20020111" and 'wafer' and 'chamfered' same 'mirror' adj1 'finished'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:58
S38	0	@ad<="20020111" and 'wafer' and 'chamfered' same 'mirror' adj1 'finished' same 'non mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:56
S39	2	@ad<="20020111" and 'wafer' and 'chamfered' same 'non mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:03
S40	3	@ad<="20020111" and 'wafer' and 'chamfered' and 'non mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:03
S41	2	@ad<="20020111" and 'wafer' and 'chamfered' and 'non-mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:03
S42	368	ota-yutaka.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:25
S43	50	ota-yutaka.in. and 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:25

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S44	77	'shin-etsu handotai' and 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 13:47
S45	33	'hitachi Itd' and 'wafer' same 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 14:19
S46	55	'wafer' same 'chamfered' same 'polish'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 14:20
S47	65	'chamfered' with 'polish'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 14:20
S48	1	"20030110803".PN.	US-PGPUB	OR	ON	2005/01/05 14:22
S49	1	"20030109202".PN.	US-PGPUB	OR	ON	2005/01/05 14:22
S50	1	"20020121110".PN.	US-PGPUB	OR	ON	2005/01/05 14:22
S51	586	@ad<="20020111" and (438/455). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:40
S52	162	@ad<="20020111" and (438/456). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:40
S53	1271	@ad<="20020111" and (438/457-460).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S54	367	@ad<="20020111" and (427/289). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S55	323	@ad<="20020111" and (257/e21. 237).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S56	395	@ad<="20020111" and (257/618). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41

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S57	251	@ad<="20020111" and (451/44). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41		
S58	170	@ad<="20020111" and (257/e21. 238).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41		
S59	252	@ad<="20020111" and (257/e21. 239).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41		
S60	303	@ad<="20020111" and (257/e21. 002).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41		
S61	189	@ad<="20020111" and (257/e21. 022).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:18		
S62	353	@ad<="20020111" and (438/690). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:33		
S63	2	"20040140536"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 08:39		
S64	560	'wafer notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 11:09		
S65	560	'wafer notch' or 'wafer chafer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 16:01		
S66	636	'wafer notch' or 'wafer chamfer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 11:11		
S67	34	'wafer notch' and 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:48		

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S68	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:04
S69	1	"5458529".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:05
S70	1	"5445554".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:06
S71	1	"5445554".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:06
S72	1	"4905425".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:06
S73	1	"5185965".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:06
S74	1	"5117590".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:07
S75	1	"4783225".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:08
S76	19	'wafer notch' same 'radius'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:36
S77	1	"6341996".PN.	USPAT; USOCR	OR	ON	2005/05/20 08:21
S78	1	"5083378".PN.	USPAT; USOCR	OR	ON	2005/05/20 08:21
S79	2	"2991555".PN.	USPAT; USOCR	OR	ON	2005/05/20 08:21
S80	220	'wafer' and 'notch' and 'radius' and 'shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:37
S81	3	'wafer' and 'notch' and 'radius' and 'shoulder' same 'arc'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:40
S82	5	'wafer' and 'shoulder' with 'circular' with 'arc'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:43
S83	3	@ad<="20040112" and 'wafer' and 'notch' same 'shoulder circular'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:45
S84	183	@ad<="20040112" and 'wafer' and 'notch' same 'shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:49

S85	4	@ad<="20040112" and 'wafer' and 'notch' same 'shoulder' same 'radius'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:46
S86	28	@ad<="20040112" and 'wafer' with 'notch' same 'shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:04
S87	17	@ad<="20040112" and 'wafer' with 'eccentric' with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:55
S88	1	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' with 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:05
S89	14	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' and 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:05
S90	2	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' same 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:05
S91	4	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' same 'radii'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:06
S92	4	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' same 'radius'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:09
S93	38	@ad<="20040112" and 'semiconductor' and 'notch' and 'shoulder' same ('curvature' or 'radius' or 'radii')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:10
S94	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:31
S95	1	"4167836".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:31
S96	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:32
S97	1	"5289661".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:32

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S98	1720	@ad<="20020111" and (451/44). ccls. or (451/258).ccls. or (451/57). ccls. or (451/65).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:34
S99	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:34
\$10 0	1	'wafer notch' and 'curvature' and 'symmetric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:13
S10 1	245	@ad<="20040112" and ('arc' or 'curcular') with 'notch' and 'symmetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:59
S10 2	30	@ad<="20040112" and ('arc' or 'curcular') with 'notch' same 'symmetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:59
S10 3	0	@ad<="20040112" and 'wafer' and ('arc' or 'curcular') with 'notch' same 'symmetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:08
S10 4	118	@ad<="20040112" and 'wafer' and ('arc' or 'curcular') with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:59
S10 5	57	@ad<="20040112" and 'wafer' same ('arc' or 'curcular') with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:59
S10 6	19	@ad<="20040112" and 'wafer' and ('arc' or 'curcular') with 'notch' and 'symmetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:38
\$10 7	31	YAMAZAKI-KEISUKE.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:24
S10 8	49	@ad<="20040112" and 'wafer' and 'notch' with 'smooth'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:40

S10 9	2	"20040113236"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:39
S11 0	4	@ad<="20040112" and 'wafer' and 'notch' with 'smooth edge'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:05
S11 1	0	@ad<="20040112" and 'semiconductor' and 'notch' with 'same shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:05
S11 2	0	@ad<="20040112" and 'semiconductor' and 'notch' with 'smooth shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:05
S11 3	90	@ad<="20040112" and 'semiconductor' and 'notch' with 'shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:07
S11 4	5	@ad<="20040112" and 'semiconductor' and 'notch' with 'same curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:08
S11 5	0	@ad<="20040112" and 'wafer' and 'notch' with 'same curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:08
S11 6	41	@ad<="20040112" and 'wafer' and 'notch' with 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:38
S11 7	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/20 14:14
S11 8	1	"5458529".PN.	USPAT; USOCR	OR	ON	2005/05/20 14:14
S11 9	0	yoshiharu-hidaka.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:29
S12 0	67	Hidaka-Yoshiharu.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:36

S12 1	6	Ikenouchi-Katsuyuki.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:00
S12 2	701	('trench' or 'via') same 'nitride' same 'oxynitride' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:01
S12 3	240	('trench' or 'via') same 'nitride' same 'oxynitride' same 'thickness' with 'angstrom'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:03
S12 4	10	('trench' or 'via') same 'liner' with 'nitride' with 'oxynitride' same 'thickness' with 'angstrom'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:15
S12 5	1	"6509266".PN.	USPAT; USOCR	OR	ON	2005/05/20 15:11
S12 6	1	"6489233".PN.	USPAT; USOCR	OR	ON	2005/05/20 15:12
S12 7	20	('trench' or 'via') same 'liner' with 'nitride' with 'oxynitride' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:28
S12 9	641	'capacitor' and 'dielectric' same 'nitride' with 'oxynitride' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:29
S13 0	99	'trench capacitor' and 'nitride' with 'oxynitride' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:29
S13 1	2	("6439969").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/29 15:37
S13 2	2	"20040113236"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:40

6/5/06 1:04:03 PM
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S13 3	683	'wafer notch' or 'wafer chamfer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:49
S13 4	35	'wafer notch' and 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:49
S13 5	35	S133 and S134	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:49
S13 6	0	@ad<="20040112" and 'wafer' and 'chamfer' and 'notch' with 'symetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/02 13:09
S13 8	44	@ad<="20040112" and 'wafer' and 'symmetrical' with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:41
S13 9	3	@ad<="20040112" and 'wafer' and 'symmetrical' with 'chamfer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:41
S14 0	2	("5185965").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/02 12:55
S14 1	3	"2001036738"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/02 09:17
S14 2	2	"20010036738"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/02 09:18
S14 3	2	("6326309").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/02 09:19
S14 4	1	"5923993".PN.	USPAT; USOCR	OR	ON	2006/06/02 09:18

S14		"5042742" DN	LICDAT	0.0	ON	0000/00/00 00:40
5	1	"5913712".PN.	USPAT; USOCR	OR	ON	2006/06/02 09:18
S14 6	2	"20020164934"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/02 09:20
S14 7	3	("6913526").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/02 13:12
S14 8	1	"6306016".PN.	USPAT; USOCR	OR	ON	2006/06/02 09:21
S14 9	1	"6220938".PN.	USPAT; USOCR	OR	ON	2006/06/02 09:21
S15 0	1	"5626511".PN.	USPAT; USOCR	OR	ON	2006/06/02 09:21
S15 1	1	"5295331".PN.	USPAT; USOCR	OR	ON	2006/06/02 09:21
S15 2	1	"5056270".PN.	USPAT; USOCR	OR	ON	2006/06/02 09:22
S15 3	1	"3686796".PN.	USPAT; USOCR	OR	ON	2006/06/02 09:22
S15 4	1	"6306016".PN.	USPAT; USOCR	OR	ON	2006/06/02 12:28
S15 5	57	"Ozaki Haruo"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/02 12:55
S15 7	295	@ad<="20040112" and wafer same notch and curvature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/02 13:09
S15 8	67	"Honda Katsuo "	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/02 13:13
S15 9	1	"6045436".PN.	USPAT; USOCR	OR	ON	2006/06/02 13:59
S16 0	1	"5727990".PN.	USPAT; USOCR	OR	ON	2006/06/02 14:00
S16 2	686	@ad<="20040112" and "semiconductor wafer" with notch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:07

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S16 4	18	@ad<="20040112" and "Ozaki haruo" and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:08
S17 3	794	@ad<="20040112" and (257/797). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:27
S17 5	663	@ad<="20040112" and (438/462). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:27
S17 6	295	@ad<="20040112" and (451/44). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:28
S17 7	590	@ad<="20040112" and (257/620). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:38
S17 8	123	@ad<="20040112" and (451/14). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:28
S17 9	663	@ad<="20040112" and (438/462). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:29
S18 0	1728	@ad<="20040112" and (451/5). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:29
S18 2	1843	@ad<="20040112" and (257/E23. 179).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:29
S18 3	495	@ad<="20040112" and (257/618). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/05 11:38